

HOSTAFORM[®] C 9021 10/1570

HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GCL, 03-002 POM copolymer Medium viscosity injection molding grade; UV-stabilized with carbon black; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. UL-registration for a thickness more than 1.5 mm as UL 94 HB, temperature index UL 746 B electrical 110 °C, mechanical 90 °C. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm. Ranges of applications: exterior applications. UL = Underwriters Laboratories (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information			
Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469
Rheological properties			
v	_	0	
Melt volume-flow rate		cm ³ /10min	ISO 1133
Temperature	190		
Load	2.16	•	
Moulding shrinkage, parallel	2.0		ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	3000	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	64	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8	%	ISO 527-1/-2
Nominal strain at break	25	%	ISO 527-1/-2
Tensile creep modulus, 1h	2500		ISO 899-1
Tensile creep modulus, 1000h	1400		ISO 899-1
Charpy impact strength, 23°C		kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C		kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C		kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30°C		kJ/m²	ISO 179/1eA
Poisson's ratio	0.37 ^[C]		
[C]: Calculated			
Thermal properties			
Melting temperature, 10°C/min	167	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	105	°C	ISO 75-1/-2
Coefficient of linear thermal expansion	110	E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Flammability			
Burning Behav. at 1.5mm nom. thickn.	HB	class	IEC 60695-11-10
Thickness tested		mm	IEC 60695-11-10
Burning Behav. at thickness h	HB	class	IEC 60695-11-10
Thickness tested	3	mm	IEC 60695-11-10
UL recognition	yes		UL 94
FMVSS Class	В		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	55.2	mm/min	ISO 3795 (FMVSS 302)





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Electrical properties

Volume resistivity Surface resistivity Electric strength Comparative tracking index		1E14	Ohm.m Ohm kV/mm	IEC 62631-3-1 IEC 62631-3-2 IEC 60243-1 IEC 60112
Physical/Other properties				
Humidity absorption, 2mm Water absorption, 2mm Density		0.2 0.65 1420		Sim. to ISO 62 Sim. to ISO 62 ISO 1183
Injection				
Drying Recommended Drying Temperature Drying Time, Dehumidified Dryer Processing Moisture Content Melt Temperature Optimum Min. melt temperature Max. melt temperature Screw tangential speed Mold Temperature Optimum Min. mould temperature Max. mould temperature Hold pressure range		no 100 3 - 4 ≤0.2 200 190 210 ≤0.3 100 80 120 60 - 120	h % °C °C °C m/s °C °C °C	
Characteristics				
Processing	Injection Moulding			
Delivery form	Pellets			

Release agent

Light stabilised or stable to light, U.V. stabilised or stable to weather

Additional information

Special characteristics

Injection molding

Additives

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D)

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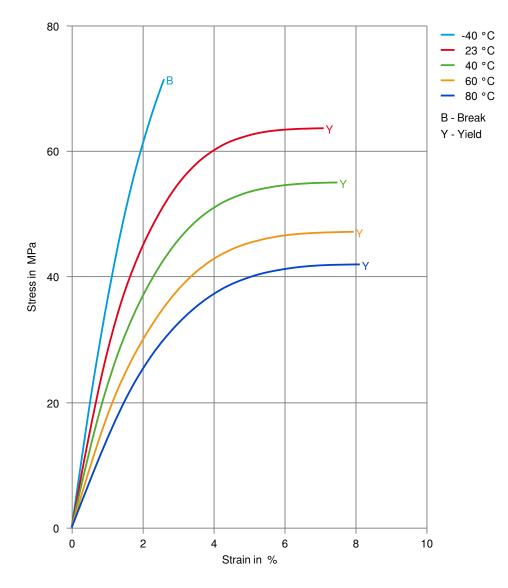
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plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.





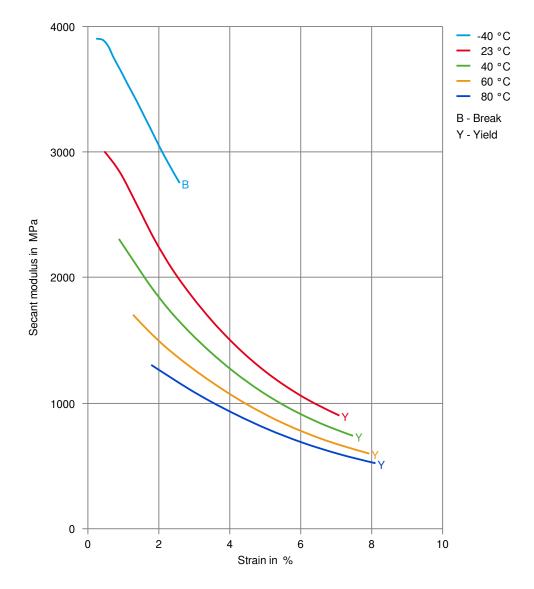




HOSTAFORM® C 9021 10/1570

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Secant modulus-strain



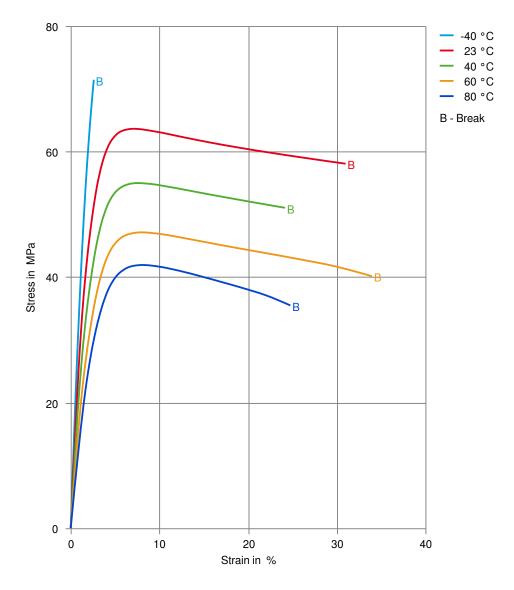




HOSTAFORM® C 9021 10/1570

HOSTAFORM®

Stress-strain, 50mm/min



Printed: 2025-05-30

Page: 5 of 5

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